

### Features

High Output Power: P5dB=45.0dBm (Typ.)

High Linear Gain: GL=12.5dB (Typ.)

High Power Added Efficiency: PAE=40% (Typ.)

· Broad Band: 6.4 to 7.2GHz

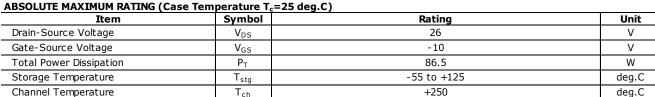
Impedance Matched Zin/Zout = 50ohm

· Hermetically Sealed Package

### Description

The SGK6472-30A is a high power GaN-HEMT that is internally matched for standard communication bands to provide optimum power and gain in a 50ohm system.





RECOMMENDED OPERATING CONDITION

Item	Symbol	Condition	Limit	Unit	
Drain-Source Voltage	$V_{DS}$		<=24	V	
Forward Gate Current	$I_{GF}$	Rg=100ohm	<=6.1	mA	
Reverse Gate Current	$I_{GR}$	Rg=100ohm	>=-3.2	mA	
Channel Temperature	T <sub>ch</sub>		<+192	deg.C	

**ELECTRICAL CHARACTERISTICS (Case Temperature T<sub>c</sub>=25 deg.C)** 

Th. a	Symbol	Condition	Limit			11
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Saturated Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V	-	6.5	-	Α
Trans Conductance	G <sub>m</sub>	V <sub>DS</sub> =24V, I <sub>DS</sub> =1.3A	-	3.0	-	S
Pinch-off Voltage	V <sub>P</sub>	V <sub>DS</sub> =24V, I <sub>DS</sub> =1.3mA	-1.5	-3	-4.5	V
Output Power at 5dB G.C.P.	P <sub>5dB</sub>		44.0	45.0	-	dBm
Linear Gain at Pin=22.5dBm	GL	$V_{DS}=24V(typ.)$	11.5	12.5	-	dB
Drain Current at 5dB G.C.P.	I <sub>DSR</sub>	I <sub>DS(DC)</sub> =1.75A(typ.) f=6.4 to 7.2 GHz	-	2.7	4.0	Α
Power Added Efficiency at 3dB G.C.P.	PAE	Vgs-constant	-	40	-	%
Gain Flatness	ΔG	- vgs constant	-	-	1.8	dB
3rd Order Inter Modulation Distortion	IM <sub>3</sub>	f=6.4GHz, 7.2GHz Δf=10MHz, 2-tone Test Pout=29.5dBm (S.C.L.)	-40.0	-45.0	-	dBc
Thermal Resistance	R <sub>th</sub>	Channel to Case $(T_c=25\text{deg.C}, \text{Pdiss}=96\text{W})$	-	2.2	2.6	deg.C/W
Channel Temperature Rise	$\Delta T_{ch}$	$(V_{DS} \times I_{DSR} - Pout + Pin) \times R_{th}$	-	85	150	deg.C
		G C P · Gain Comr	ression Po	int SCI	· Single	Carrier Level

G.C.P.: Gain Compression Point, S.C.L.: Single Carrier Level

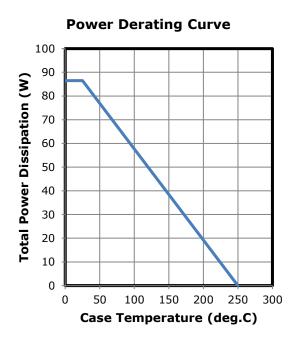
CASE STYLE	IBK	
RoHS Compliance	YES	
ESD	Class 1C	1000V to < 2000V

Note: Based on ANSI/ESDA/JEDEC JS-001-2012(C=100pF, R=1.5kohm)

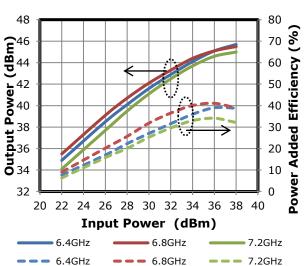


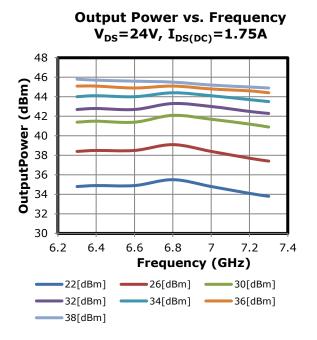


### RF Characteristics

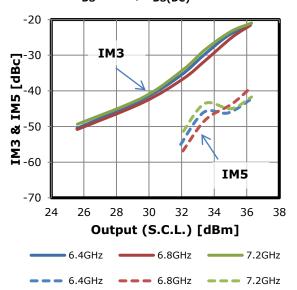


Output Power & Power Added Efficiency vs. Input Power  $V_{DS}$ =24V,  $I_{DS(DC)}$ =1.75A





IMD vs. Output Power(S.C.L.)  $V_{DS}$ =24V,  $I_{DS(DC)}$ =1.75A



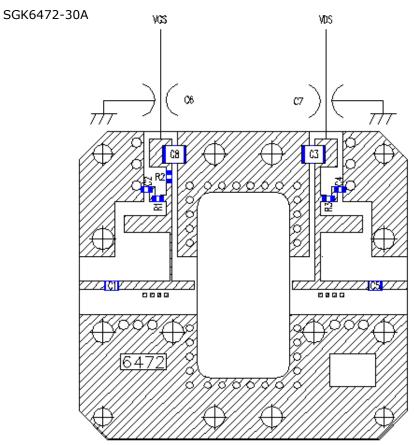


## • S-Parameter

Freq.	S11		S21 S12		S12		S22	
	MAG	ANG I	MAG	ANG	MAG	ANG	MAG	ANG
6200MHz	0.603	14.8	4.461	-58.1	0.086	-132.7	0.154	-135.6
6300MHz	0.573	4.1	4.484	-69.8	0.089	-144.0	0.154	-161.7
6400MHz	0.531	-7.0	4.519	-81.6	0.092	-155.7	0.175	173.6
6500MHz	0.483	-18.4	4.560	-93.9	0.095	-167.5	0.209	152.3
6600MHz	0.424	-30.4	4.603	-106.5	0.097	-179.6	0.253	134.2
6700MHz	0.355	-43.6	4.621	-119.3	0.099	167.5	0.302	118.4
6800MHz	0.279	-58.5	4.635	-132.7	0.101	154.8	0.356	103.5
6900MHz	0.197	-77.6	4.616	-146.5	0.101	141.3	0.41	89.7
7000MHz	0.118	-107.8	4.568	-160.4	0.102	128.1	0.461	76.3
<b>7100MHz</b>	0.079	-173.7	4.461	-174.5	0.101	114.5	0.507	63.0
<b>7200MHz</b>	0.126	128.5	4.307	171.6	0.098	100.8	0.544	49.9
7300MHz	0.198	102.2	4.135	158.0	0.096	87.6	0.569	37.1
7400MHz	0.264	86.0	3.952	145.2	0.092	75.0	0.582	25.3



# • Amplifier Circuit Outline



3.0pF
1000pF
0.1uF
1000pF
3.0pF
1000pF
1000pF
0.1uF
51ohm
100ohm
51ohm

Substrate: Rogers RO4003C

h=0.542mm, er=3.38

Cu=18um

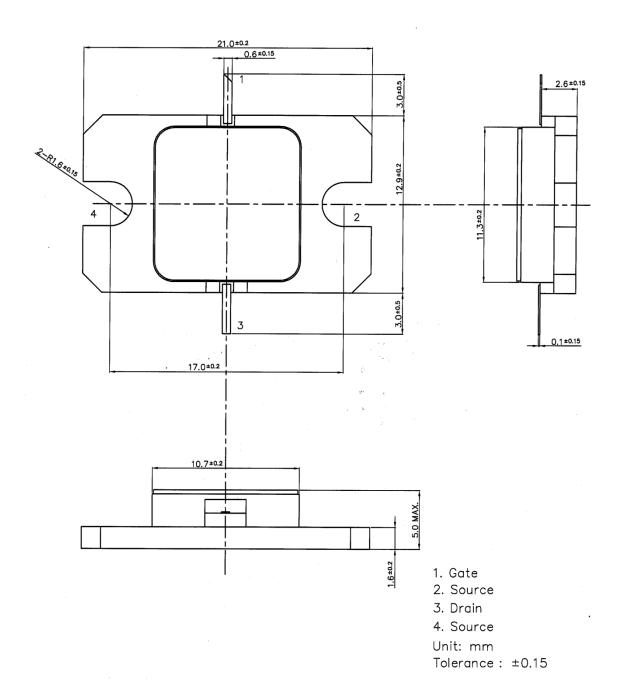
C1, C5: ATC600L(size:0805), +/- 0.1pF

C6, C7: EMI FILTER MARUWA(FTA352AR102S-S)



## • Package Out line

Case Style : IBK





### For Safety, Observe the Following Procedures Environmental Management

- Do not put this product into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or swallowed.
- Respect all applicable laws of the country when discarding this product.
  This product must be disposed in accordance with methods specified by applicable hazardous waste procedures.

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Edition 1.1 Jan. 2021